MACOM Technology Solutions Inc.
100 Chelmsford Street
Lowell, Massachusetts 01851
www.macom.com

April 12, 2022

Digi-Key Corporation
701 Brooks Ave South
Thief River Falls, Minnesota 56701

ATTN: Quality/Purchasing Manager

Subject: Substrate plating change to standard process

PCN #: PCN-01528

Dear Valued Customer:

The goal of MACOM Technology Solutions is to continually deliver high quality products and services that meet our customers' needs. We strive to offer products that are industry leading in terms of performance, delivery and value.

In accordance with these goals, this communication is to inform you that MACOM is making a plating change to the ceramic substrate used in the following devices.

LM102202-Q-A-301-R	LM200802-M-A-300
LM102202-Q-C-301	LM102202-Q-C-301-T
LM501202-M-C-300-T	LX501202-M-C-300
LM102202-Q-B-301	LM102202-Q-B-301-R
LM202802-M-C-300	LM102202-Q-A-301-T
LM102202-Q-B-301-T	LM501202-M-C-300-R
LM200802-M-A-300-T	

You are receiving this notice because you have purchased the above product in the past two years.

Please contact your local sales representative if you have any questions or require additional information.

Sincerely,

Tom Woodward
Product Engineering Manager
MACOM Technology Solutions, Inc.
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PCN Number: PCN-01XXX		**PCN Date: April 12, 2022**
Title: Metallization/Plating change		
Date of change: April 2022 **Proposed last Ship Date:**		**Estimated Sample Availability/ Qualification Completion:** On request
Change Classification:	**Major** ☐	**Minor** ☒
Change Type:		
Assembly Site ☐	Design ☐	Electrical Specification ☐
Test Site ☐	Assembly Process ☐	Mechanical Specification ☐
Test Process ☐	Assembly Materials ☒	Packing/Shipping/Labeling ☐

PCN Details

Description of Change:

Updating the plating to standardize processing. Changes shown below.

Current Metalization:

METALLIZATION: FRONT AND BACK METAL
(750-1500) Å TiW (SPUTTERED)
(5000±500) Å Ni (SPUTTERED)
-FRONTSIDE: 50µ INCHES MIN. Au (PLATED)
-BACKSIDE: (10-20) µ INCHES Au (PLATED

New Metallization:

- TOPSIDE METAL A1:
  TIW: 1000-1500Å (SPUTTERED)
  NI: 7-9uIN (SPUTTERED) AU: 55-65uIN (SPUTTERED)
- TOPSIDE METAL A2:
  CU: 18-22uIN (SPUTTERED)
  CU: 800uIN MIN. (PLATED)
  NI: 40-80uIN (PLATED)
  AU: 30uIN MAX. (PLATED)

- BACKSIDE METAL: TIW: 1000-1500Å (SPUTTERED)
  NI: 18-22uIN (SPUTTERED)
  AU: 16-18uIN (SPUTTERED)

Reason for Change:

Standardize ceramic substrate metallization and plating across this product portfolio.

Products Affected:

See front page

Anticipated impact on Fit, Form, Function:
There will be no impact on fit, form, function, or reliability by this change.
Changes to product identification resulting from this PCN:
None.
Material Declaration updated due to this change: Yes ■ No ☐